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SPE® THERMOSET DIV. ANNOUNCES FIRST KEYNOTE FOR TOPCON 2020:
“THERMOSETS – A HISTORICAL AND FUTURE PERSPECTIVE” WILL BE PRESENTED BY
PROFESSOR TIM A. OSSWALD, DIRECTOR OF THE POLYMER ENGINEERING CENTER (PEC)
AT THE UNIVERSITY OF WISCONSIN-MADISON

The SPE Thermoset Div. is announcing its first keynote speaker for their annual TopCon event to be held on May 12 – 13, 2020 at the Monona Terrace and Convention Center in Madison, Wisconsin. “THERMOSETS – A HISTORICAL AND FUTURE PERSPECTIVE,” will be presented by Professor Tim A. Osswald, Director of the Polymer Engineering Center (PEC) at the University of Wisconsin-Madison. His presentation will take the audience through time, from the “heat and pressure” patent application in 1907, through the growth of an industry now known as the thermoset plastics industry. This growth also included an entirely different branch of the plastics field, namely, the composites industry; from asbestos filled Bakelite to unsaturated polyester fiber glass panels during the Second World War, to a growing SMC (Sheet Molding Compound) automotive body panel industry all the way to today’s aerospace applications. Finally, the presentation will take a look into the future of thermosets through the emerging 3D printing field, including hybrid structures where the synergy of great thermosetting materials are combined into a light-weight product that is better than each of its individual components.

Osswald is also Honorary Professor of Plastics Technology at the University of Erlangen-Nuremberg in Germany and the National University of Colombia. His research includes modeling and simulation in polymer processing, engineering design with plastic and composite materials, and sustainability in
plastics manufacturing. Professor Osswald served as the Chief English Language Editor for the “Journal of Polymer Technology” and Editor for the “Americas for the Journal of Polymer Engineering”.

He has published over 300 peer-reviewed conference and journal articles as well as 15 books translated in five languages, including: “International Plastics Handbook” (2019), “Polymer Processing – Modeling and Simulation” (2006), “Understanding Polymer Processing” (2017), and “Materials Science of Polymers for Engineering” (2012). Professor Osswald has also served as an expert witness in polymer engineering litigation, including product failure, patents and intellectual property and is on the advisory board of multiple companies. He is currently adviser to the President of Colombia in the creation of a new Ministry for Science, Technology, and Innovation.

The SPE Thermoset TopCon 2020 will feature technical presentations and exhibits highlighting advances in materials, processes, and equipment for thermoset technologies in electrical, automotive, off-highway, appliance, aerospace, building and construction, oil and gas, and other industries. The conference includes one full day of technical sessions with a networking breakfast, lunch and cocktail reception on May 12, and a networking breakfast on May 13. Optional social events, including a golf outing at University Ridge Golf Course, a tour of the Polymer Engineering Center (PEC) at the University of Wisconsin-Madison, and a cruise of the Madison shoreline via private yacht with deluxe appetizers and beverages are offered on May 11, the day before the conference begins.

Conference Venue:

Inspired by Wisconsin native Frank Lloyd Wright’s design, at the peak of his creative powers in 1938, the Monona Terrace Community and Convention Center is one of the country’s premier conference and convention facilities. On the shores of Lake Monona, it is an architecturally striking structure that connects the state capital, the cityscape, and the community. The conference exhibits, meals and cocktail reception will be in the Community Terrace with pristine views of Lake Monona offering a relaxing and enjoyable experience. The presentations will be in the Lecture Hall offering comfortable theatre style seating, staging and professional audio-visual support. Special rates are provided for conference attendees at the Hilton Madison Monona Terrace which is connected via skywalk to the conference venue. See https://www.mononaterrace.com and https://www3.hilton.com/ for more info.
Sponsors:

SPE Thermoset TopCon 2020 sponsors to date include: Mar-Bal, Inc.; WesTool Corporation; Plenco (Plastics Engineering Company); Glenwood Tool & Mold, Inc.; Omya AG; Chromaflo Technologies; Huber Engineered Materials; IDI Composites; Fox Valley Molding, Inc.; ICT Molding Solutions; American Colors, Cimbar, AOC Aliancys, Molding Products, Penn Compression, LyondellBasell and Composites One.

The mission of SPE is to promote scientific and engineering knowledge relating to composites worldwide and to educate industry, academia, and the public about the technological advances. SPE’s Thermoset Division is active in educating, promoting, recognizing, and communicating technical accomplishments in thermoset technology in multiple industries. Topic areas include applications, materials, processing, equipment, tooling, design, and development.

For more information see https://spethermosets.org/topcon/For more information on the Society of Plastics Engineers, see www.4spe.org.

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Professor Tim A. Osswold, Director of the Polymer Engineering Center (PEC) at the University of Wisconsin-Madison